ABSTRACT

The invention provides a method for permanently physically and electrically attaching the electrically conductive contacts of a first component in a RFID device, such as a smart card or smart inlay, to the electrically conductive contacts of a second component of the device. Attachment is made between the first and second components of the device by co-depositing metal and electrically conductive hard particles upon the conductive contacts of either the first or second components and using a non-conductive adhesive to provide permanent bond between the components and their conductive contacts. Components of an RFID device may include, for example, a memory chip, a microprocessor chip, a transceiver, or other discrete or integrated circuit device, a chip carrier, a chip module, and a conductive area, e.g., an antenna.